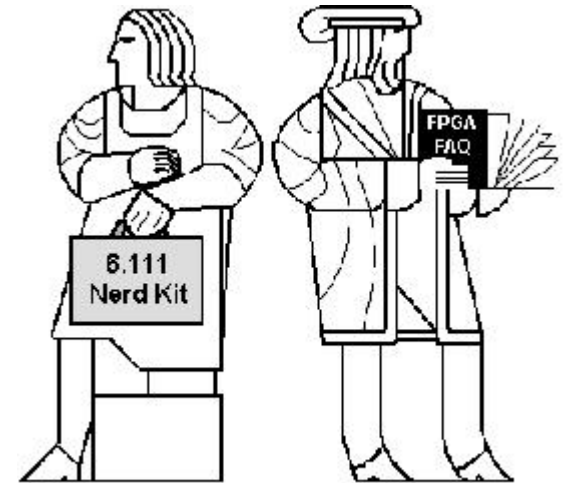


6.111 Lecture 8

Today: Memories

1. Static RAMs
2. Interfacing: Bus & Protocol
3. Synchronous Memories
4. EPROMs and DRAMs
5. Memory Mapped Peripherals



Acknowledgement: Nathan Ickes, Rex Min

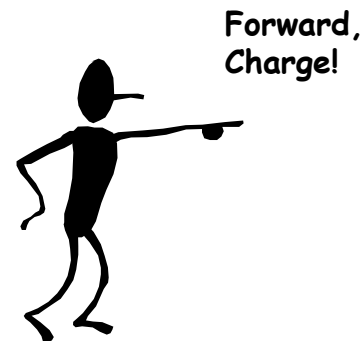
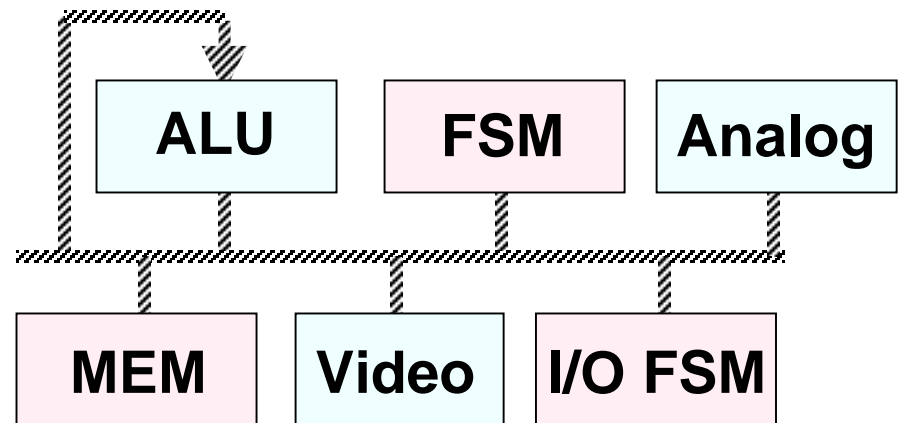
J. Rabaey, A. Chandrakasan, B. Nikolic, "Digital Integrated Circuits: A Design Perspective"
Prentice Hall, 2003 (Chapter 10)

Perspective - Our Course Ahead

Done with Lab 1. Where do we go from here?

Digital Systems!

1. Memories
2. System Integration
3. Reconfigurable Logic
4. Arithmetic Circuits
5. Analog Building Blocks
6. Video
7. Power Dissipation
8. Computer Architecture

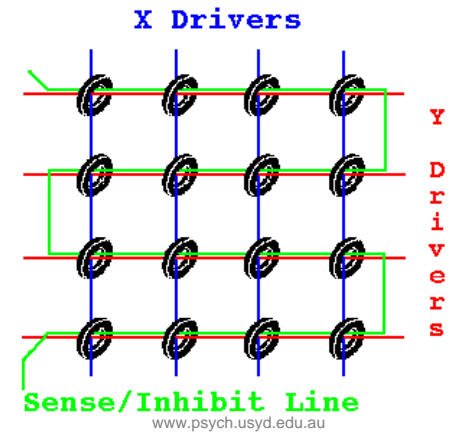


Memories of a Digital World

Why need memories? State machines...

Memories:

- **Flip Flips, Registers, FIFO** (first-in-first-out)
- **Core memory!**
- **Random Access** (static/dynamic, read/write)
- **Slow / Non-volatile** (hard drive/eeprom/eprom)
- **Content-addressable**
- **Concept of a BUS and use of TRISTATE!**



Key Design Metrics:

1. **Memory Density** (number of bits/ μm^2) and **Size**
2. **Access Time** (time to read or write) and **Throughput**
3. **Power Dissipation**

Memory Classification & Metrics

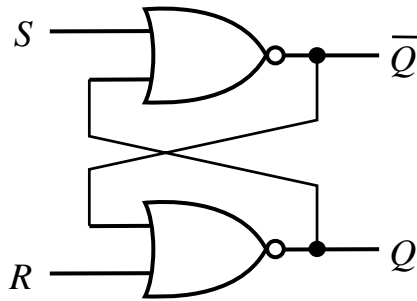
Read-Write Memory		Non-Volatile Read-Write Memory	Read-Only Memory (ROM)
Random Access	Non-Random Access	EPROM E ² PROM	Mask-Programmed
SRAM DRAM	FIFO LIFO	FLASH	

Key Design Metrics:

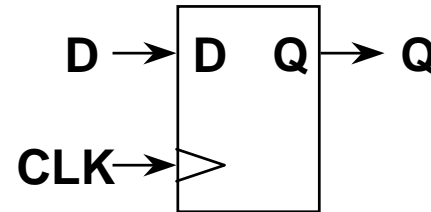
1. Memory Density (number of bits/ μm^2) and Size
2. Access Time (time to read or write) and Throughput
3. Power Dissipation

1. Static RAMs: Latch Based Memory

Set Reset Flip Flop

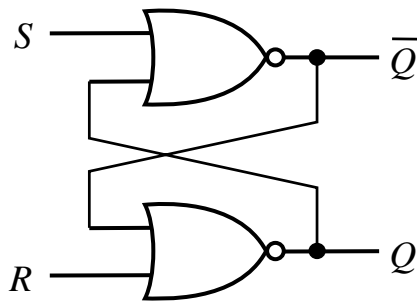


Register Memory

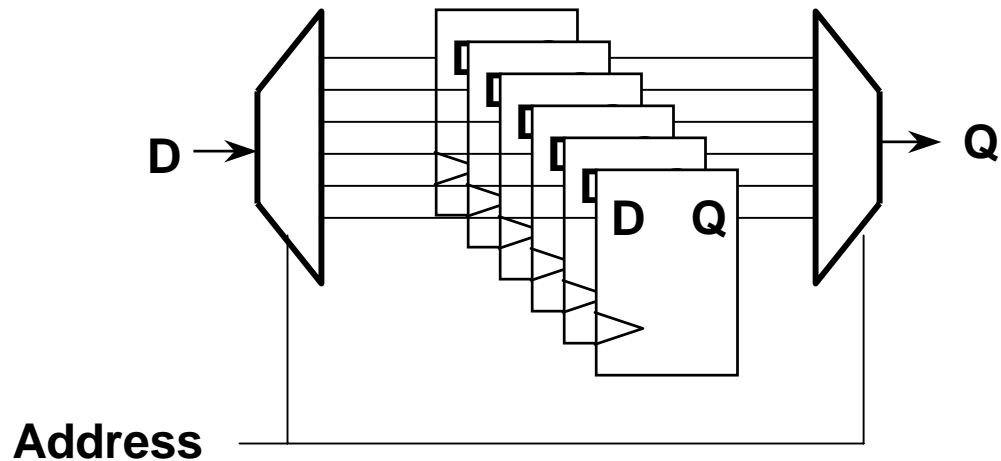


1. Static RAMs: Latch Based Memory

Set Reset Flip Flop



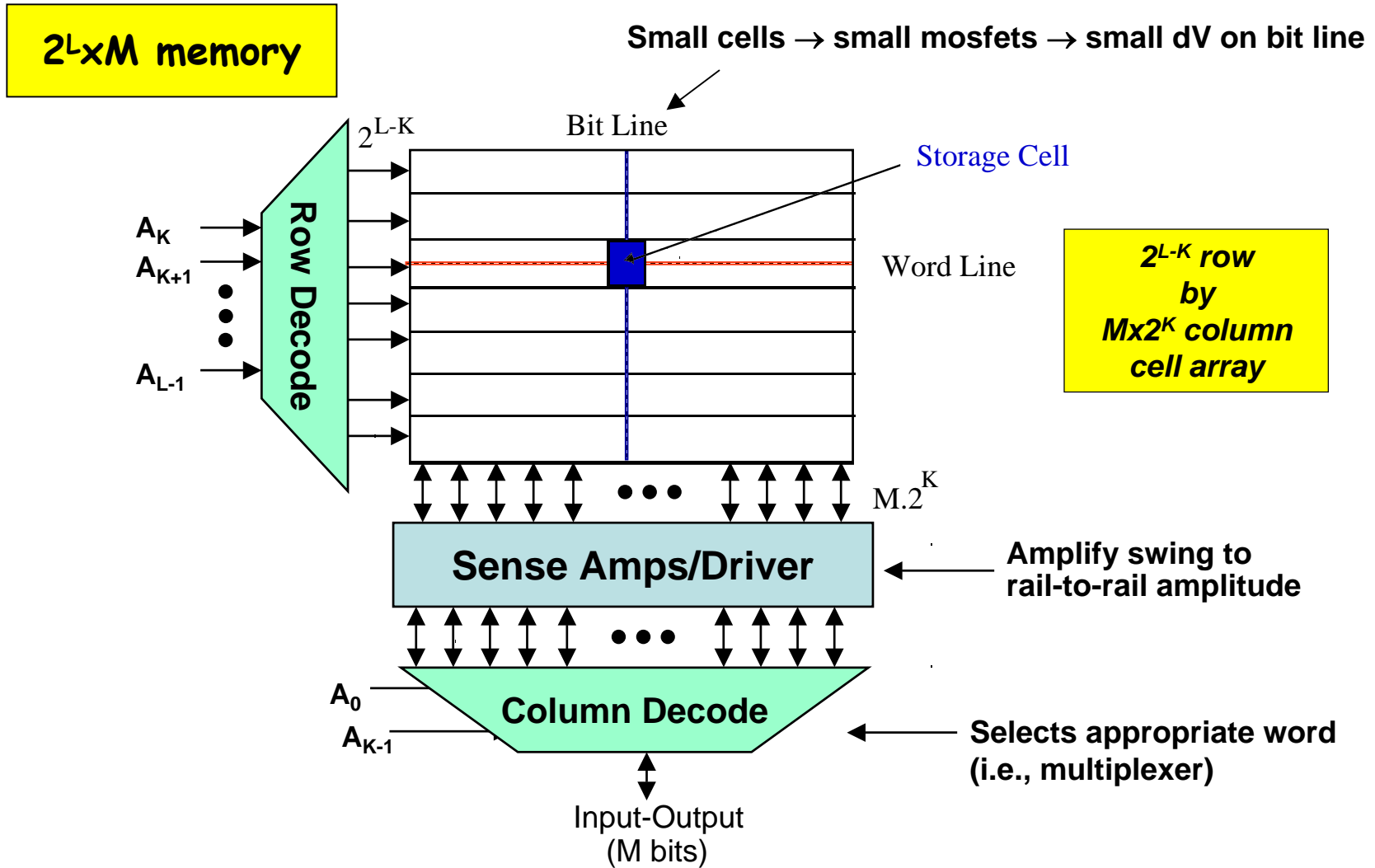
Register Memory



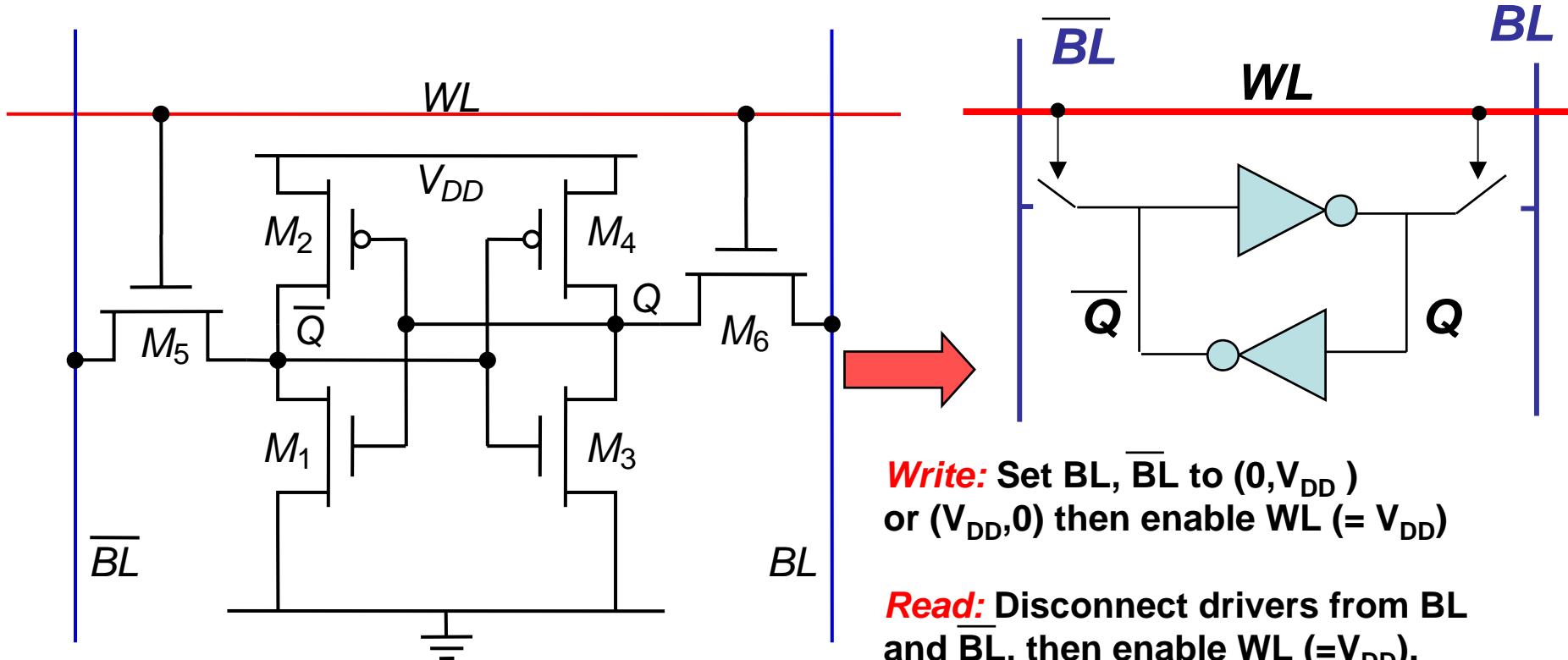
- Works fine for small memory blocks (e.g., small register files)
- Inefficient in area for large memories
- Density is the key metric in large memory circuits

How do we minimize cell size?

Memory Array Architecture



Static RAM (SRAM) Cell (The 6-T Cell)

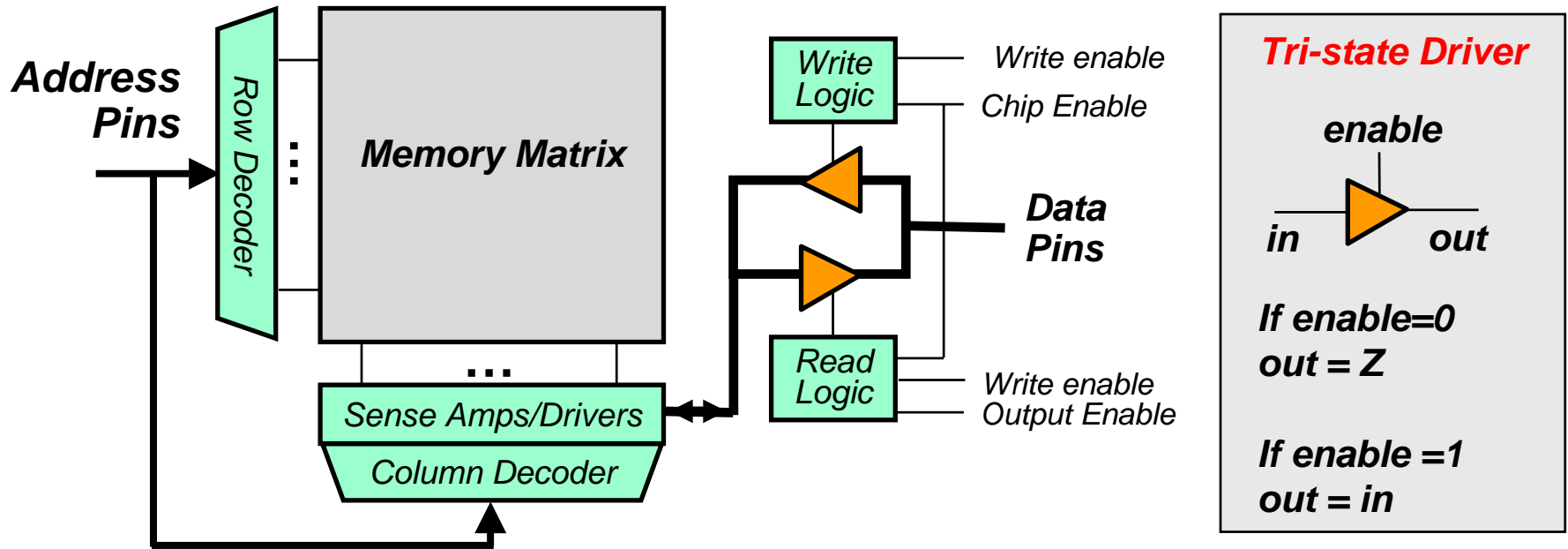


Write: Set BL , \bar{BL} to $(0, V_{DD})$ or $(V_{DD}, 0)$ then enable $WL (= V_{DD})$

Read: Disconnect drivers from BL and \bar{BL} , then enable $WL (= V_{DD})$. Sense a small change in BL or \bar{BL}

- **State held by cross-coupled inverters (M1-M4)**
- Retains state as long as power supply turned on
- Feedback must be overdriven to write into the memory

2. Interacting with a Memory Device



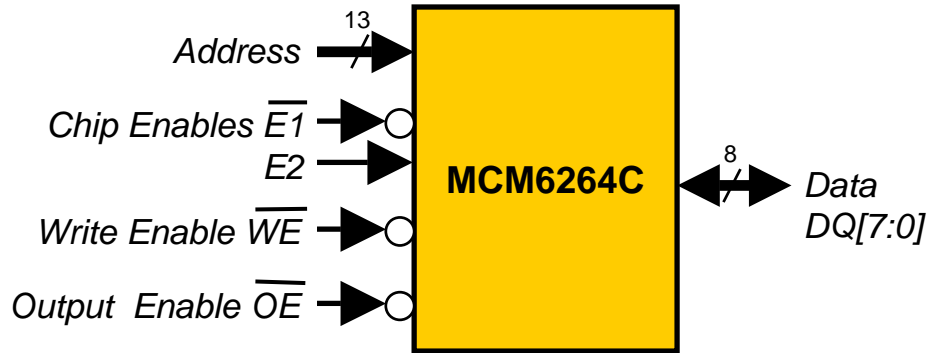
- **Address** pins drive row and column decoders
- **Data** pins are **bidirectional**: shared by reads and writes

Concept of "Data Bus"

- **Output Enable** gates the chip's tristate driver
- **Write Enable** sets the memory's read/write mode
- **Chip Enable/Chip Select** acts as a "master switch"

MCM6264C 8K x 8 Static RAM

On the outside:



Same (bidirectional) data bus used for reading and writing

Chip Enables ($\overline{E1}$ and $E2$)

$\overline{E1}$ must be low and $E2$ must be high to enable the chip

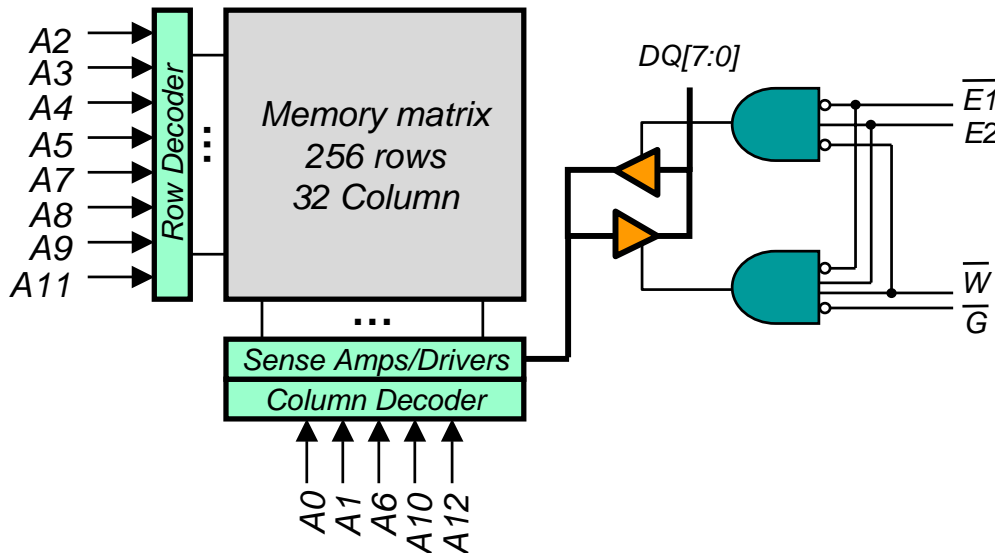
Write Enable (\overline{WE})

When low (and chip enabled), values on data bus are written to location selected by address bus

Output Enable (\overline{OE} or \overline{G})

When low (and chip is enabled), data bus is driven with value of selected memory location

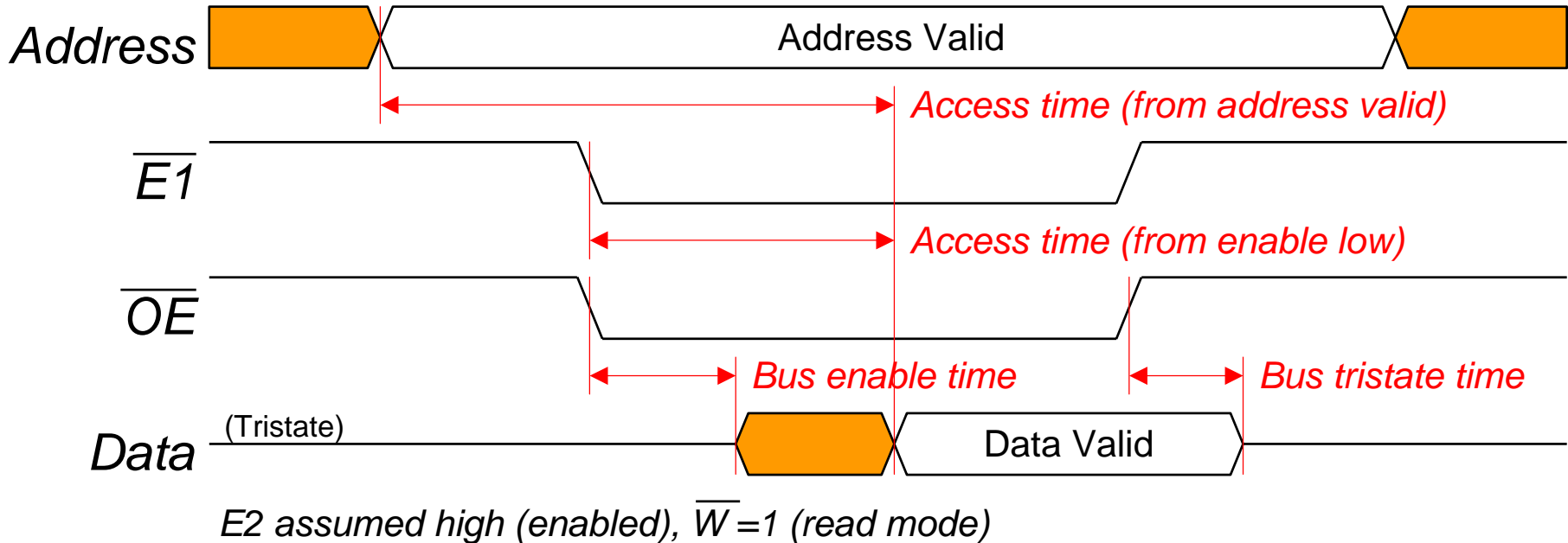
On the inside:



Pinout

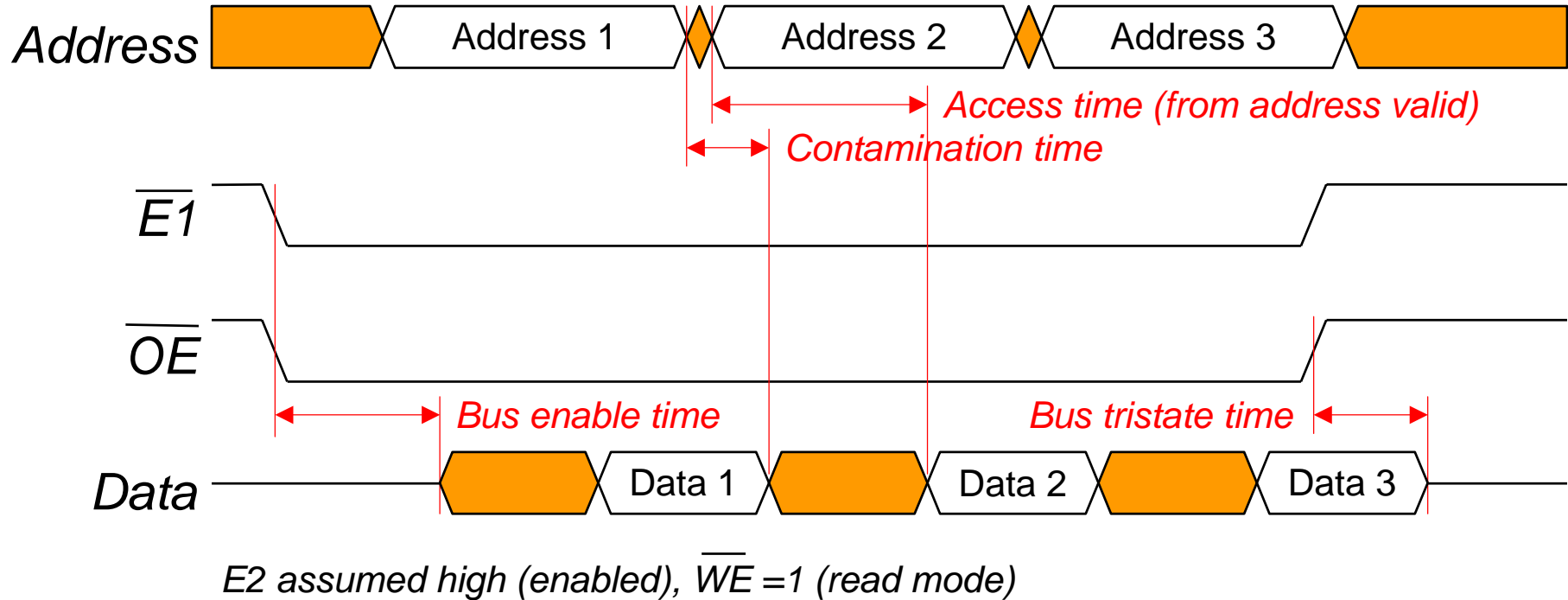
NC	1	28	VCC
A12	2	27	\overline{W}
A7	3	26	E2
A6	4	25	A8
A5	5	24	A9
A4	6	23	A11
A3	7	22	\overline{G}
A2	8	21	A10
A1	9	20	$\overline{E1}$
A0	10	19	DQ7
DQ0	11	18	DQ6
DQ1	12	17	DQ5
DQ2	13	16	DQ4
VSS	14	15	DQ3

Reading an Asynchronous SRAM



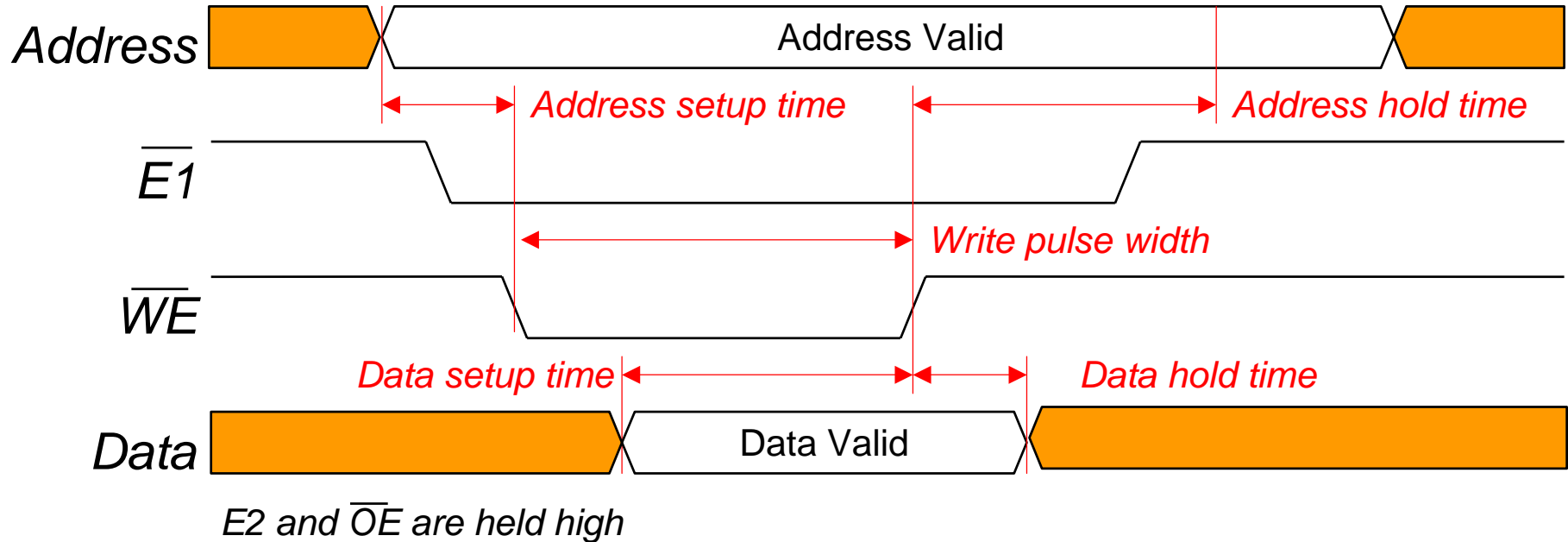
- Read cycle begins when all enable signals ($\overline{E1}$, $E2$, \overline{OE}) are active
- Data is valid after read access time
 - Access time is indicated by full part number: *MCM6264CP-12* \rightarrow 12ns
- Data bus is tristated shortly after \overline{OE} or $\overline{E1}$ goes high

Address Controlled Reads



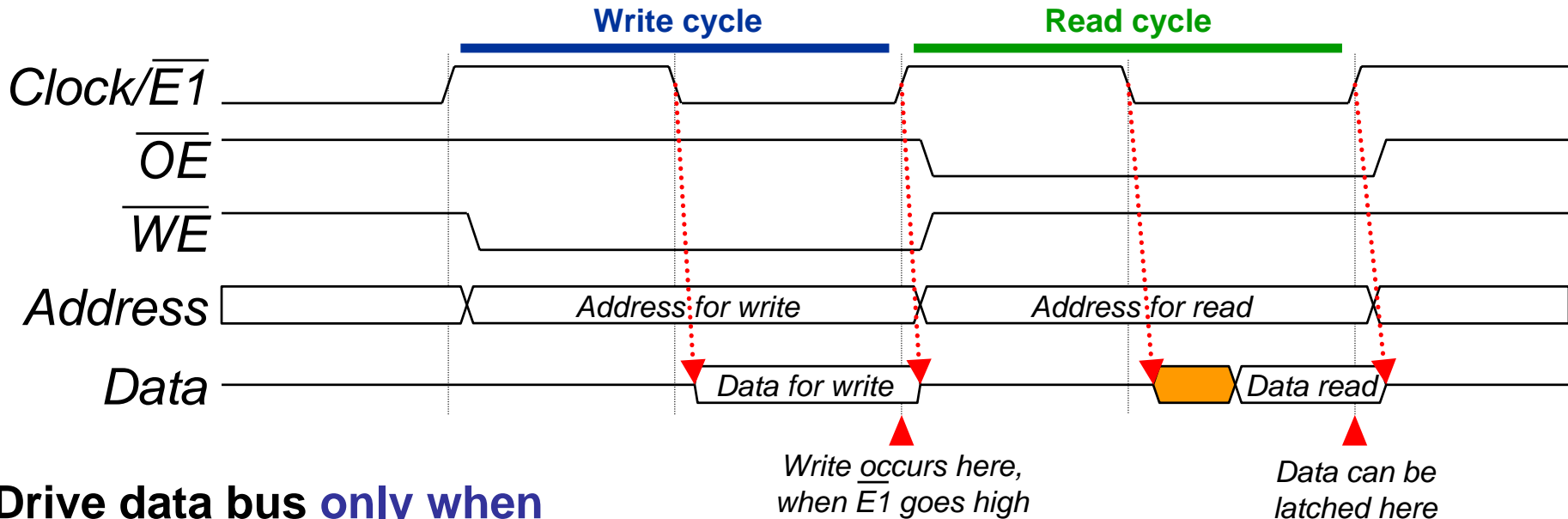
- Can perform multiple reads without disabling chip
- Data bus follows address bus, after some delay

Writing to Asynchronous SRAM



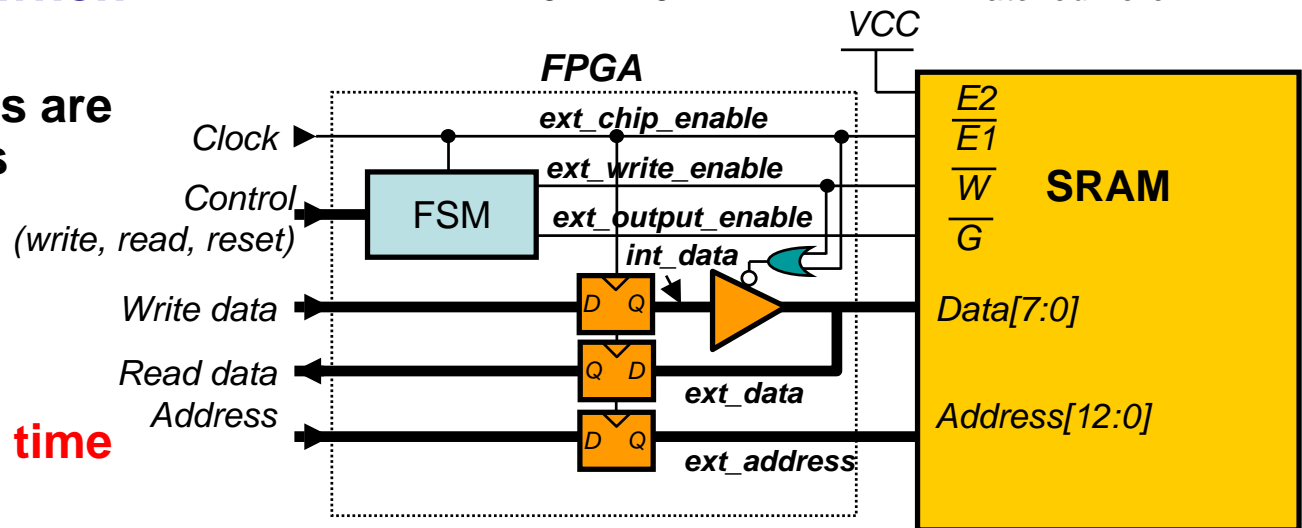
- Data latched when \overline{WE} or $\overline{E1}$ goes high (or E2 goes low)
 - Data must be stable at this time
 - Address must be stable before \overline{WE} goes low
- Write waveforms are more important than read waveforms
 - Glitches to address can cause writes to random addresses!

Sample Memory Interface Logic



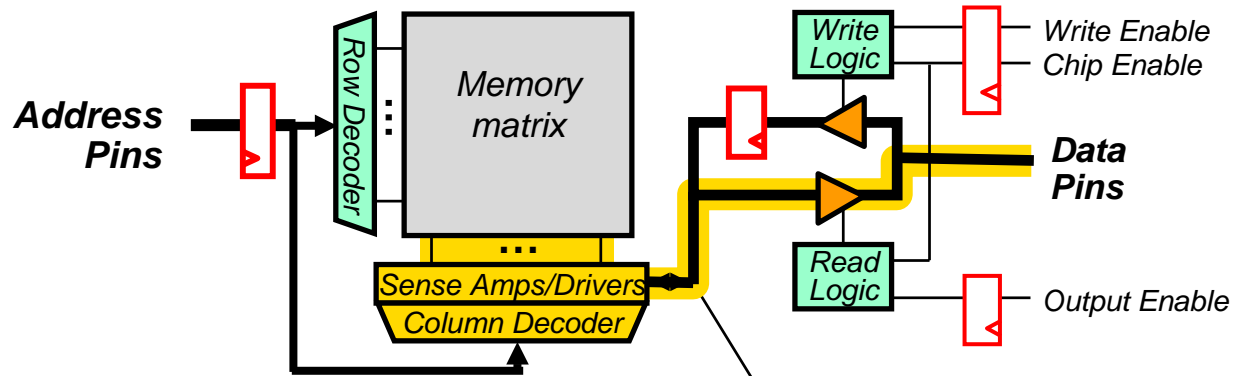
Drive data bus only when clock is low

- Ensures address are stable for writes
- Prevents bus contention
- **Minimum clock period is twice memory access time**



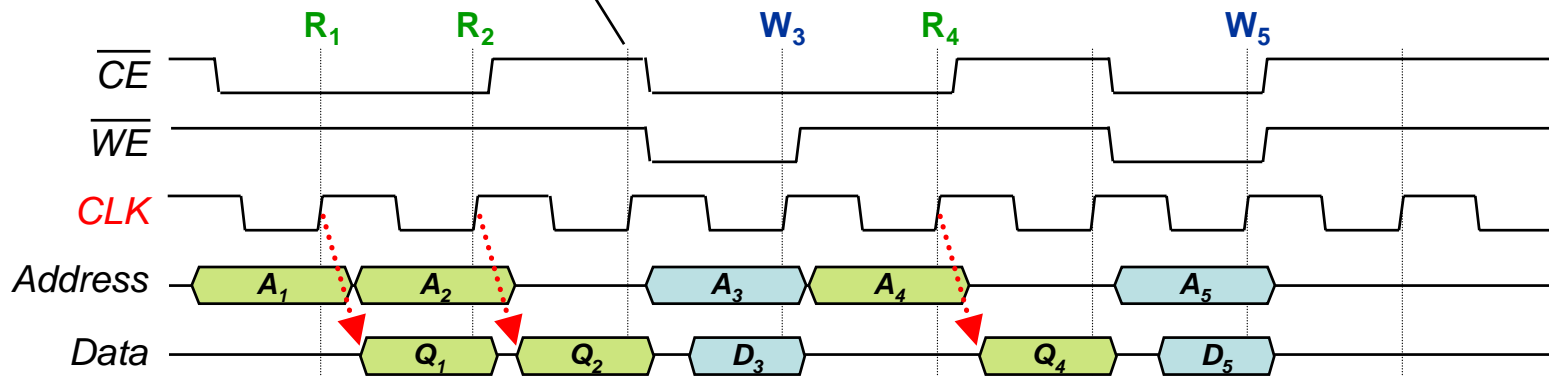
3. Synchronous SRAM Memories

- **Clocking** provides input synchronization and encourages more reliable operation at high speeds



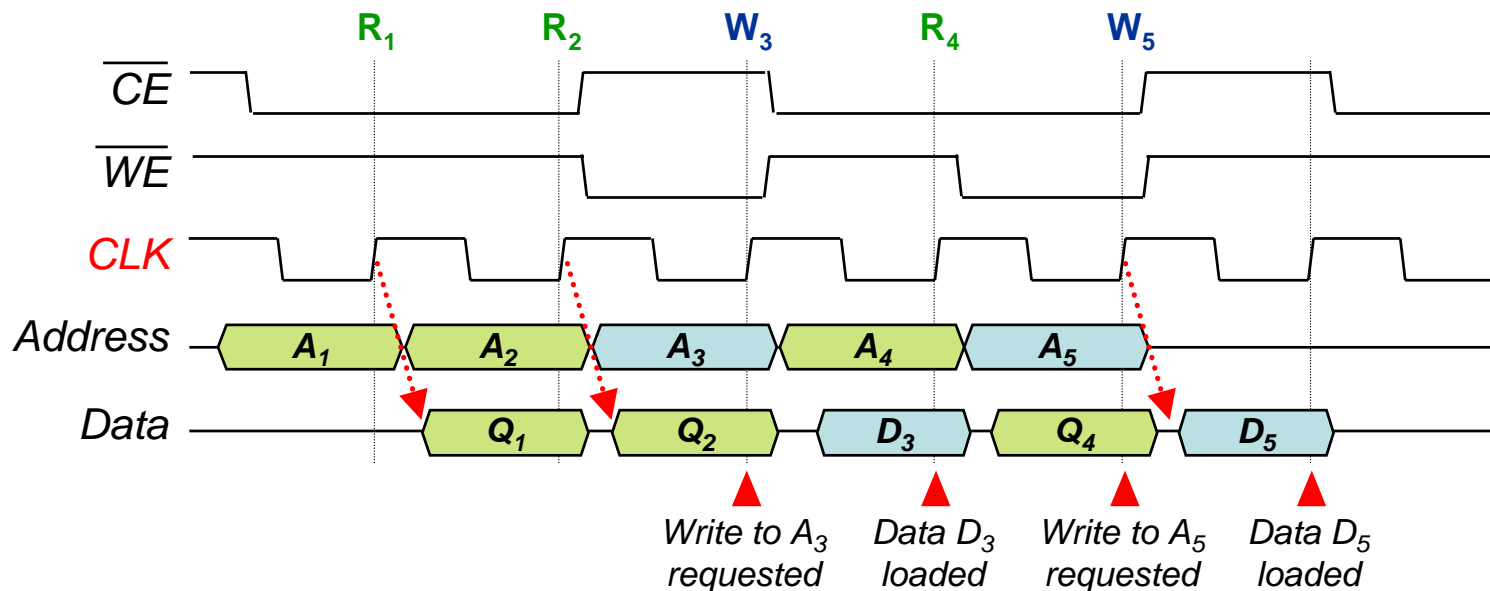
difference between read and write timings creates wasted cycles ("wait states")

long "flow-through" combinational path creates high CLK-Q delay



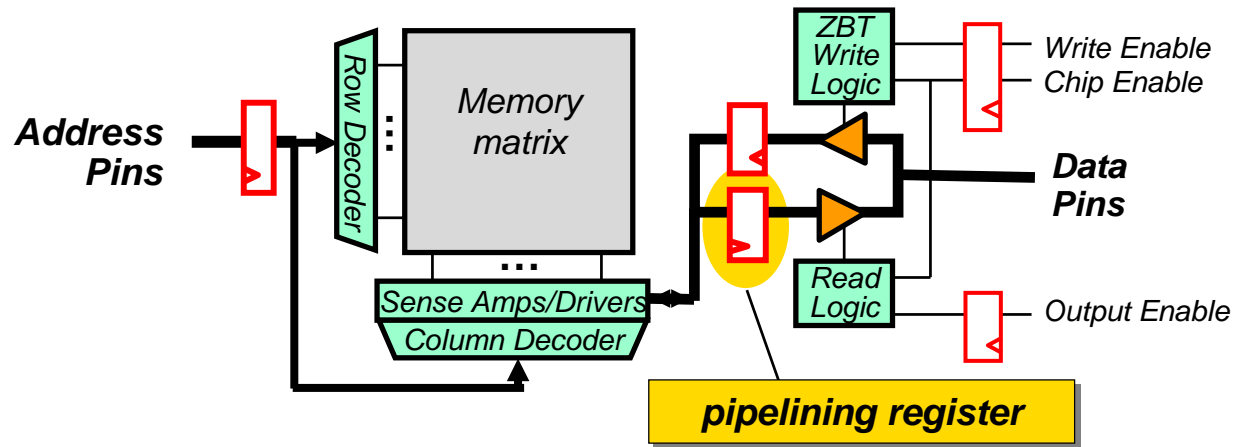
ZBT Eliminates the Wait State

- The wait state occurs because:
 - On a read, data is available *after* the clock edge
 - On a write, data is set up *before* the clock edge
- ZBT (“zero bus turnaround”) memories **change the rules for writes**
 - On a write, data is set up **after** the clock edge (so that it is read on the following edge)
 - Result: no wait states, higher memory throughput

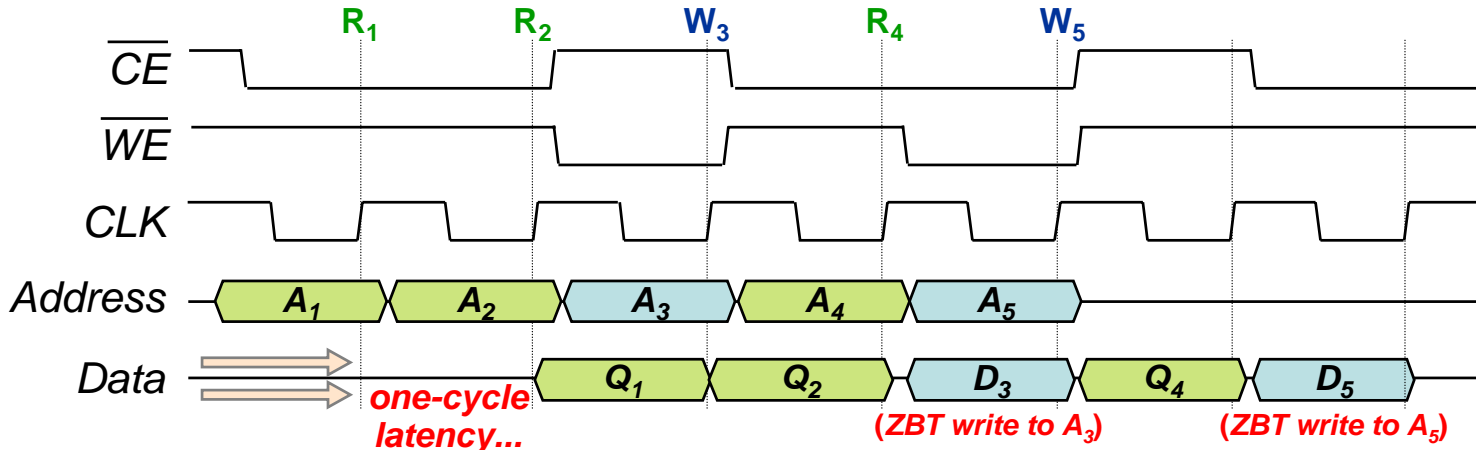


Pipelining Allows Faster CLK

- Pipeline the memory by registering its output
 - Good: Greatly reduces CLK-Q delay, allows higher clock (more throughput)
 - Bad: Introduces an extra cycle before data is available (more latency)



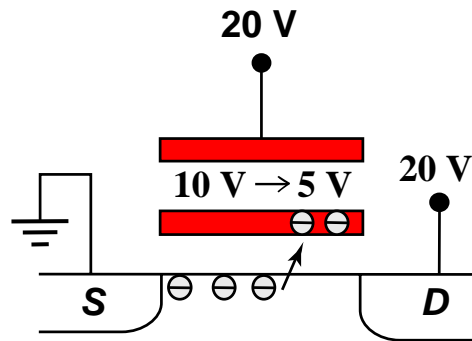
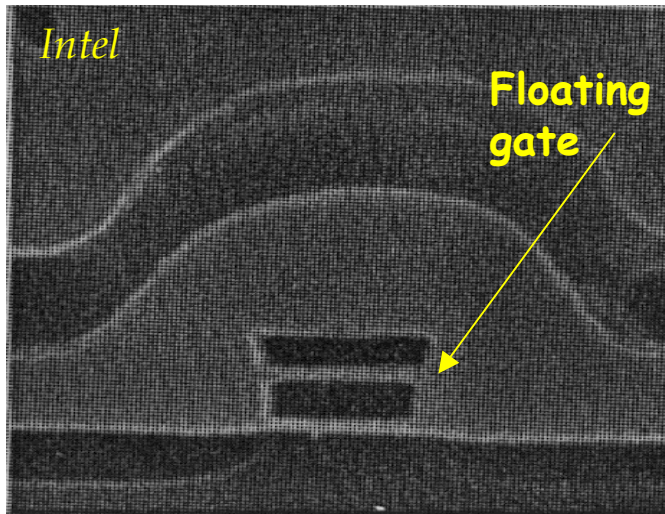
As an example,
see the **CY7C147X**
ZBT Synchronous
SRAM



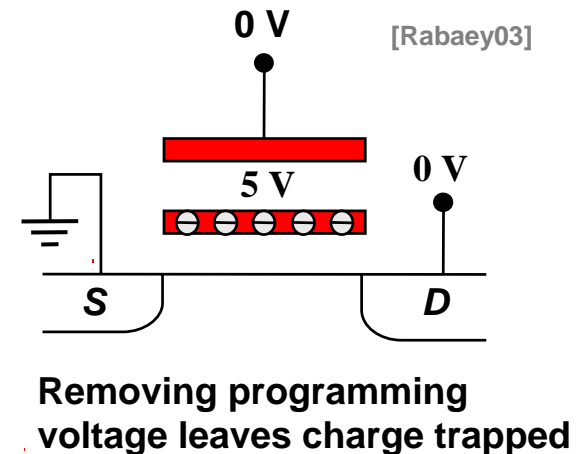
4. EPROMs and DRAMs

EEPROM - The Floating Gate Transistor

Electrically Erasable Programmable Read-Only Memory



Avalanche injection



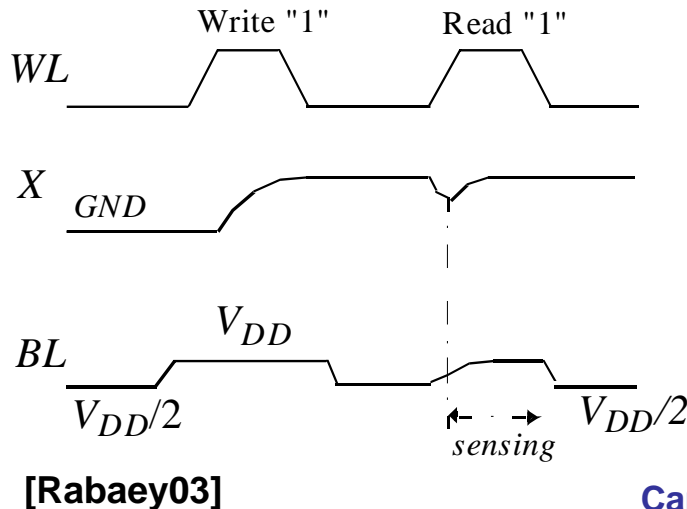
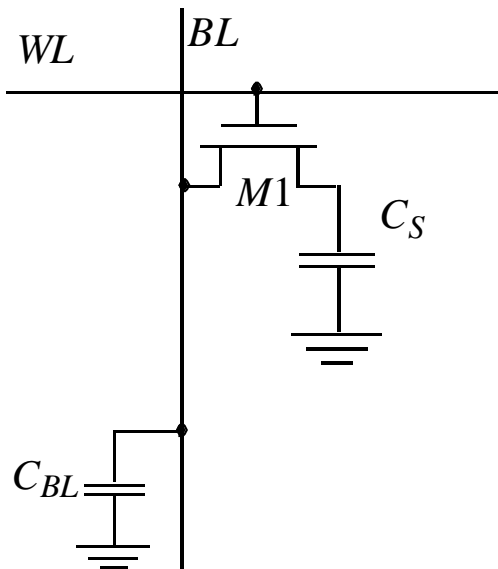
Removing programming voltage leaves charge trapped

This is a non-volatile memory (retains state when supply turned off)

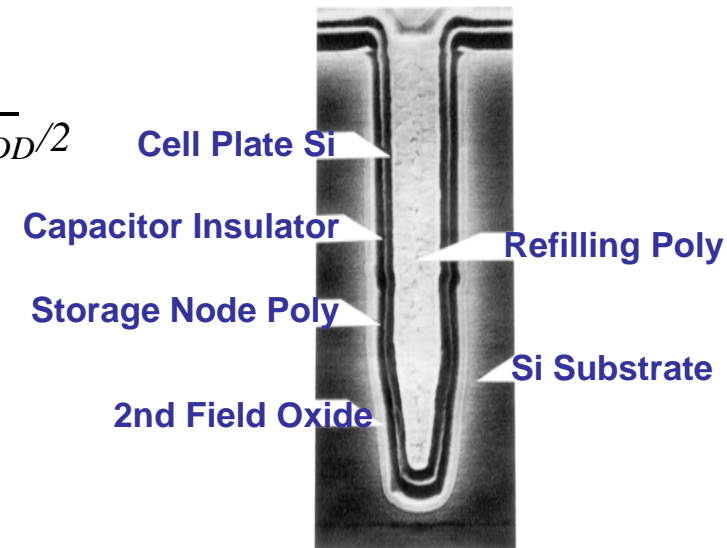
Usage: Just like SRAM, but **writes are much slower** than reads
(write sequence is controlled by an FSM internal to chip)

Common application: configuration data (serial EEPROM)

Dynamic RAM (DRAM) Cell



DRAM uses Special Capacitor Structures

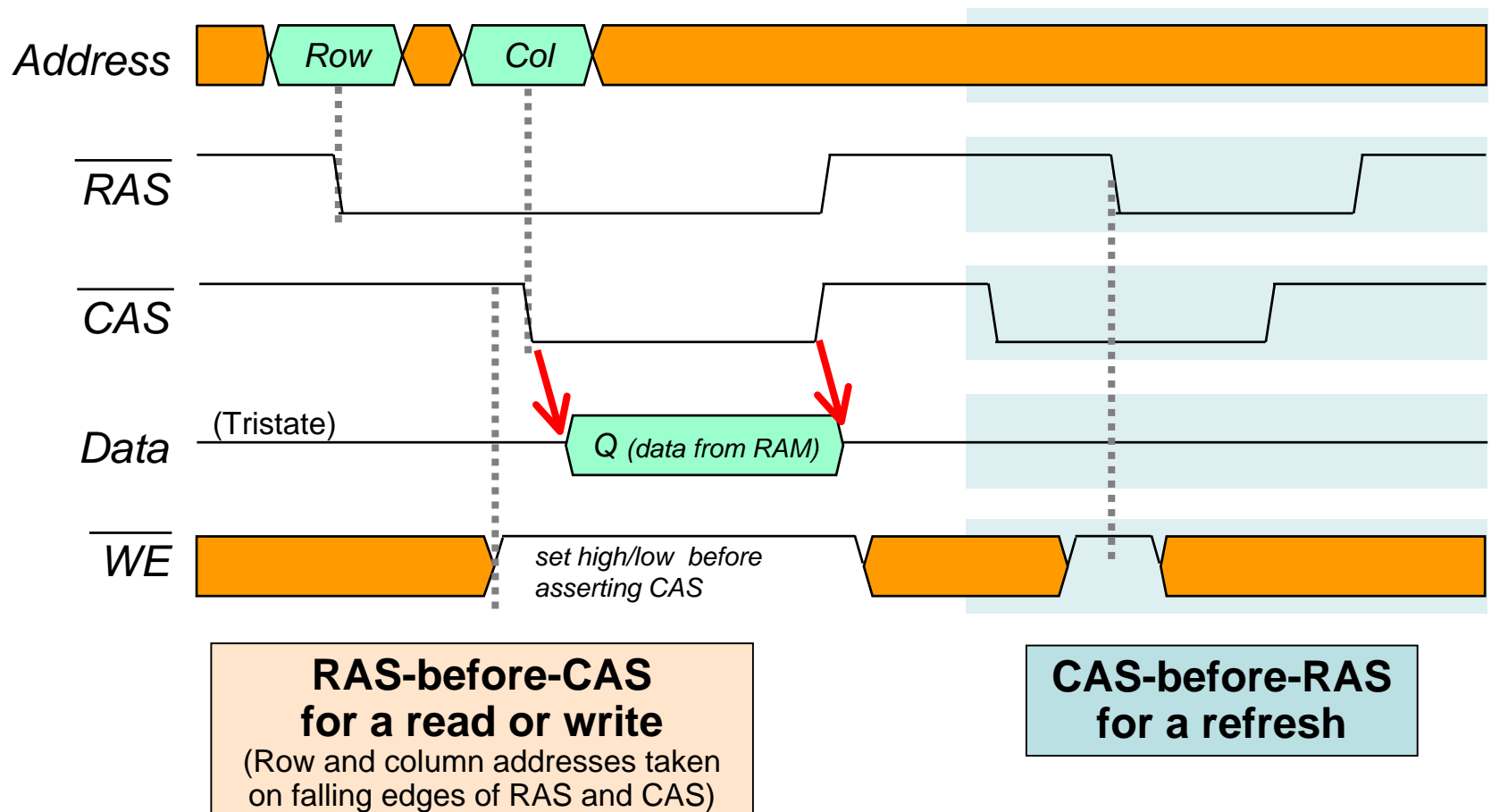


To Write: set Bit Line (BL) to 0 or V_{DD} & enable Word Line (WL) (i.e., set to V_{DD})

To Read: set Bit Line (BL) to $V_{DD}/2$ & enable Word Line (i.e., set it to V_{DD})

- **DRAM relies on charge stored in a capacitor to hold state**
- Found in all high density memories (one bit/transistor)
- Must be “refreshed” or state will be lost – high overhead

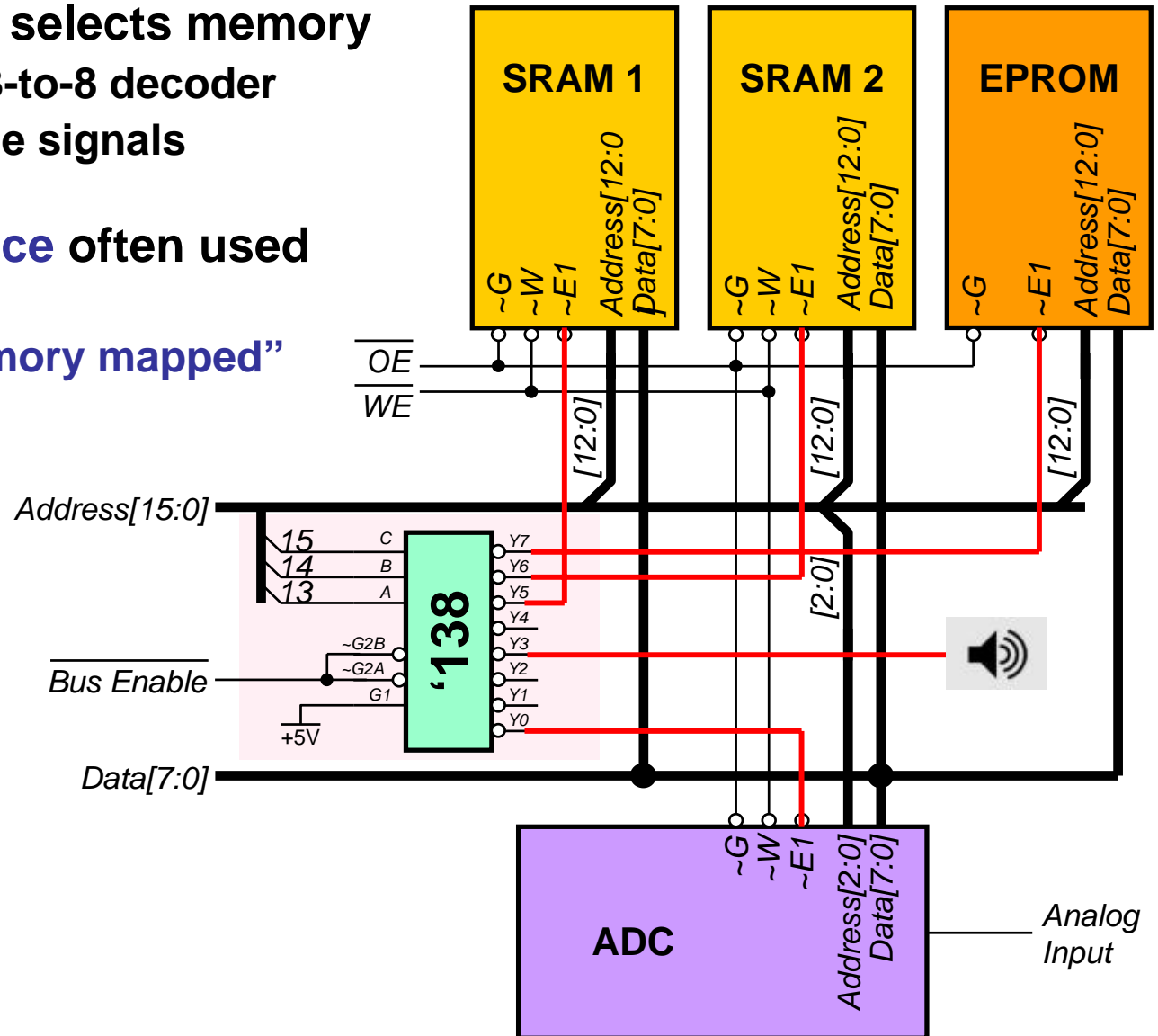
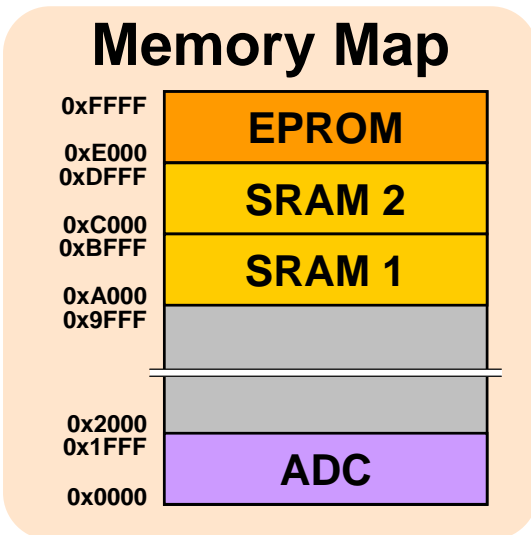
Asynchronous DRAM Operation



- **Clever manipulation of RAS and CAS after reads/writes provide more efficient modes: early-write, read-write, hidden-refresh, etc. (See datasheets for details)**

5. Addressing with Memory Maps

- Address decoder selects memory
 - Example: '138 3-to-8 decoder
 - Produces enable signals
- SRAM-like interface often used for peripherals
 - Known as “memory mapped” peripherals



Memory Devices: Helpful Knowledge

- **SRAM vs. DRAM**

- SRAM holds state as long as power supply is turned on. DRAM must be "refreshed" - results in more complicated control
- DRAM has much higher density, but requires special capacitor technology.
- FPGA usually implemented in a standard digital process technology and uses SRAM technology

- **Non-Volatile Memory**

- Fast Read, but very slow write (EPROM must be removed from the system for programming!)
- Holds state even if the power supply is turned off

- **Memory Internals**

- Has quite a bit of analog circuits internally -- pay particular attention to noise and PCB board integration

- **Device details**

- Don't worry about them, wait until 6.012 or 6.374

Summary

- **SRAMs:**

- Use synchronous FSM for interface
- Faster than DRAM, no refresh required

- **Data bus:**

- Tri-state (Z) used when not driving bus
- Multiple devices can share one bus

- **EEPROM:**

- Useful for config. data, long-term storage

- **Memory-Mapping:**

- Interact with peripheral as if it were an SRAM

